

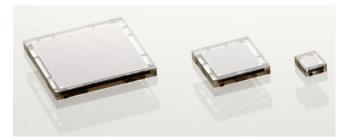
C-Series Low Noise, Fast, Blue-Sensitive Silicon Photomultipliers DATASHEET



Low Noise, Fast, Blue-Sensitive Silicon Photomultipliers

SensL's C-Series low-light sensors feature an industry-leading low dark-count rate, combined with high PDE that extends much further into the blue part of the spectrum using a high-volume, P-on-N silicon process. For ultrafast timing applications select C-Series sensors have a fast output, previously introduced in SensL's M-Series & B-Series sensors. These fast signals can have rise times of 300ps and pulse widths of 600ps. The C-Series is available in different sensor sizes (1mm, 3mm and 6mm) and packaged in a variety of formats, including a 4-side tileable surface mount (SMT) package that is compatible with industry standard, lead-free, reflow soldering processes. C-Series sensors are pin-for-pin compatible with the B-Series.

The C-Series Silicon Photomultipliers (SiPM) form a range of high gain, single-photon sensitive, UV to visible light sensors. They have performance characteristics similar to a conventional PMT, while benefiting from the practical advantages of solid-state technology: low operating voltage, excellent temperature stability, robustness, compactness, output uniformity, and low cost. For more information on the C-Series devices please refer to the website, www.sensl.com.



PERFORMANCE PARAMETERS

Sensor Size	Microcell Size	Parameter ¹	Overvoltage	Min.	Тур.	Max.	Units
1mm	10μ, 20μ, 35μ, 50μ						
3mm	20μ, 35μ, 50μ	Breakdown Voltage (Vbr)3		24.40	24.65	24.90	V
6mm	35μ						
1mm	10μ, 20μ, 35μ, 50μ						
3mm	20μ, 35μ, 50μ	Recommended overvoltage Range (Voltage above Vbr) ²		1.0	5.0	5.0	V
6mm	35μ	riango (voltago abovo vol)					
1mm	10μ, 20μ, 35μ, 50μ						
3mm	20μ, 35μ, 50μ	Spectral Range 4		300		800	nm
6mm	35μ						
1mm	10μ, 20μ, 35μ, 50μ						
3mm	20μ, 35μ, 50μ	Peak Wavelength (λp)			420		nm
6mm	35μ						

¹ All measurements made at 2.5V overvoltage and 21°C unless otherwise stated.

² Please consult the maximum current levels on page 6 when selecting the overvoltage to apply.

³ The breakdown voltage (Vbr) is defined as the value of the voltage intercept of a parabolic line fit to the current vs. voltage characteristic curve.

⁴ SMT package spectral range is limited from 320nm to 800nm. X13 package extends UV response to 300nm.





Sensor Size	Microcell Size	Parameter	Overvoltage	Min.	Тур.	Max.	Units
	10μ				14		%
4	20μ		\/h		24		%
1mm	35μ		Vbr + 2.5V		31		%
	50μ				35		%
1mm	10μ				18		%
	20μ		Vbr + 5.0V		31		%
	35μ		VDF + 5.0V		41		%
	50μ	PDE ⁵ at λp			47		%
	20μ	PDE - at xp			24		%
3mm	35μ		Vbr + 2.5V		31		%
	50μ				35		%
	20μ				31		%
3mm	35μ		Vbr + 5.0V		41		%
	50μ				47		%
6mm	35μ		Vbr + 2.5V		31		%
6mm	35μ		Vbr + 5.0V	41			%
	10μ		Vbr + 2.5V		2x10 ⁵		
1mm	20μ				1x10 ⁶		
	35μ				3x10 ⁶		
	50μ	Gain			6x10 ⁶		
	20μ	(anode to cathode readout)			1x10 ⁶		
3mm	35μ				3x10 ⁶		
	50μ				6x10 ⁶		
6mm	35μ			3x10 ⁶			
	10μ				5.2x10 ³		
1	20μ				4.3x10 ⁴		
1mm	35μ		\/\.\.\.\.\.\.\.\.\.\.\.\.\.\.\.\.\.\.\		4.3x10 ⁴		
	50μ	Gain			4.3x10 ⁴		
	20μ	(fast terminal readout)	Vbr + 2.5V		4.3x10 ⁴		
3mm	35μ				4.3x10 ⁴		
	50μ				4.3x10 ⁴		
6mm	35μ				4.3x10 ⁴		
	10μ				1	3	nA
1mm	20μ				5	16	nA
1mm	35μ				15	49	nA
	50μ	Double Co	\/br + 0.5\/		32	102	nA
	20μ	Dark Current ⁶	Vbr + 2.5V		50	142	nA
3mm	35μ				154	443	nA
	50μ				319	914	nA
6mm	35μ				618	1750	nA

⁵ Note this is true "sensor PDE" which does not contain afterpulsing or crosstalk.

⁶ Dark current derived from dark count data as DC*M*q*(1+CT)*(1+AP), where DC is dark count, M is gain, q is the charge of an electron, CT is cross talk and AP is afterpulsing.





Sensor Size	Microcell Size	Parameter	Overvoltage	Min.	Тур.	Max.	Units
	10μ				30	96	kHz
	20μ				30	96	kHz
1mm	35μ				30	96	kHz
	50μ) // O 5) /		30	96	kHz
	20μ	Dark Count Rate	Vbr + 2.5V		300	860	kHz
3mm	35μ				300	860	kHz
	50μ				300	860	kHz
6mm	35μ				1200	3400	kHz
1mm	10μ, 20μ, 35μ, 50μ				0.3		ns
3mm	20μ, 35μ, 50μ	Rise Time - Fast Output 7	Vbr + 2.5V		0.6		ns
6mm	35μ				1.0		ns
1mm	10μ, 20μ, 35μ, 50μ				0.6		ns
3mm	20μ, 35μ, 50μ	Signal Pulse Width - Fast Output (FWHM)	Vbr + 2.5V		1.5		ns
6mm	35μ	Output (FVVHIVI)			3.2		ns
	10μ				10		ns
1mm 2	20μ		Vbr + 2.5V		90		ns
	35μ				180		ns
	50μ	Microcell recovery time 8			350		ns
	20μ				90		ns
3mm	35μ				180		ns
	50μ				350		ns
6mm	35µ				210		ns
	10μ				50		pF
	20μ				90		pF
1mm	35μ				100		pF
	50μ	Capacitance 9	Vbr + 2.5V		110		pF
	20μ	(anode-cathode)			770		pF
3mm	35μ				850		pF
	50μ				920		pF
6mm	35μ				3400		pF
	10μ				1		pF
	20μ				1		pF
1mm	35μ				1		pF
	50μ	Capacitance ⁹	\ (\ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \		1		pF
	20μ	(fast terminal to cathode)	Vbr + 2.5V		20		pF
3mm	35μ				12		pF
	50μ				7		pF
6mm	35μ				48		pF

⁷ Measured as time to go from 10% to 90% of the peak amplitude.

⁸ Time for microcell to recharge (90% to 10% of pulse peak amplitude).

⁹ Internal capacitance of the sensor. Typically add 2-3pF for sensor in package. Listed by unique microcell size for each part version.





Sensor Size	Microcell Size	Parameter	Overvoltage	Min.	Тур.	Max.	Units
1mm	10μ, 20μ, 35μ, 50μ						
3mm	20μ, 35μ, 50μ	Temperature dependence of Vbr 10			21.5		mV/°C
6mm	35μ						
1mm	10μ, 20μ, 35μ, 50μ						
3mm	20μ, 35μ, 50μ	Temperature dependence of Gain 11			-0.8		%/°C
6mm	35μ	Jan					
	10μ				0.6		%
4	20μ			3 7	%		
1mm	35μ	Crosstalk	Vbr + 2.5V		7		%
	50μ				10		%
	20μ				3		%
3mm	35μ				7		%
	50μ				10		%
6mm	35μ				7		%
	10μ				0.2		%
4	20μ				0.2		%
1mm	35μ				0.2		%
	50μ	After a leter	\/\ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \		0.6		%
	20μ	Afterpulsing	Vbr + 2.5V		0.2		%
3mm	35μ				0.2		%
	50μ				0.6		%
6mm	35μ				0.2		%

¹⁰ Calculated as the change in Vbr extracted from pulsed laser gain measurements.

 $^{^{11}}$ Quoted as the percentage change per degree C from the measured value at 21 $^{\circ}\text{C}.$





GENERAL PARAMETERS

	10000 series	30000 series	60000 series
	10010, 10020, 10035, 10050	30020, 30035, 30050	60035
Active area	1 x 1 mm ²	3 x 3 mm ²	6 x 6 mm ²
No. of microcells	10010: 2880 10020: 1296 10035: 576 10050: 324	30020: 10998 30035: 4774 30050: 2668	60035: 18980
Microcell fill factor	10010: 28% 10020: 48% 10035: 64% 10050: 72%	30020: 48% 30035: 64% 30050: 72%	60035: 64%

SMT Package Specifics					
	10000 series	10000 series 30000 series			
	10010, 10020, 10035, 10050	30020, 30035, 30050	60035		
Package dimensions	1.5 x 1.8 mm ²	4 x 4 mm ²	7 x 7 mm ²		
Recommended operating temperature range		-40°C to +85°C			
Recommended storage temperature range	-40°C to +85°C				
Soldering conditions	Lead-free, reflow soldering process compatible (MSL 3 for tape & reel quantities; MSL 4 for tape only qty.) See the SMT Handling Tech Note for more details.				
Encapsulant type	Clear transfer molding compound				
Encapsulant refractive Index	1.54 @ 589nm				

X18 Package Specifics (1mm only)					
	10000 series	30000 series	60000 series		
	10010, 10020, 10035, 10050	30020, 30035, 30050	60035		
Recommended operating temperature range	-40°C to +85°C				
Recommended storage temperature range	-40°C to +95°C				
Soldering conditions	Soldering iron, maximum of 260°C for no more than 10 sec. See the Soldering Tech Note for more details.				

X13 Package Specifics (3mm & 6mm only)					
	10000 series	30000 series	60000 series		
	10010, 10020, 10035, 10050	30020, 30035, 30050	60035		
Recommended operating temperature range		0°C to +40°C			
Recommended storage temperature range		-20°C to +50°C			
Soldering conditions		Soldering iron, max. of 260°C for 5sec, 2mm from ceramic base. See the Soldering Tech Note for more details.			
Encapsulant material		Ероху			



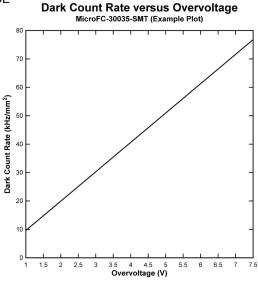


Maximum current levels for each sensor size and package type						
Package type	10000 series 30000 series		60000 series			
	10010, 10020, 10035, 10050	30020, 30035,30050	60035			
SMT	2mA	15mA	20mA			
X18	4mA	-	-			
X13	-	3mA	5mA			

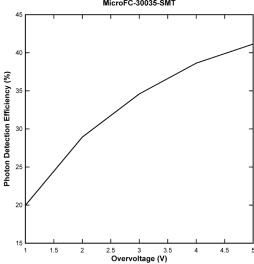




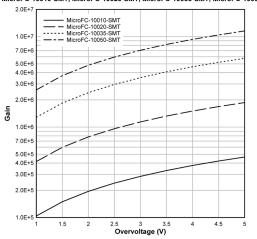
PERFORMANCE



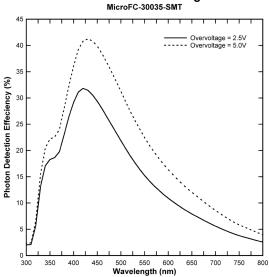
PDE at 420nm versus Voltage MicroFC-30035-SMT



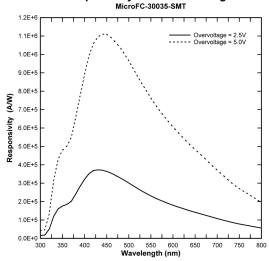
Gain versus Overvoltage MicroFC-10010-SMT, MicroFC-10020-SMT, MicroFC-10035-SMT, MicroFC-10050-SM



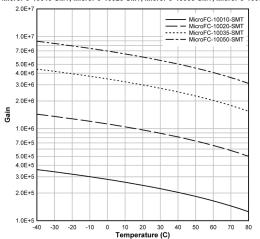
PDE versus Wavelength



Responsivity versus Wavelength



Gain versus Temperature * MicroFC-10010-SMT, MicroFC-10020-SMT, MicroFC-10035-SMT, MicroFC-10050-S



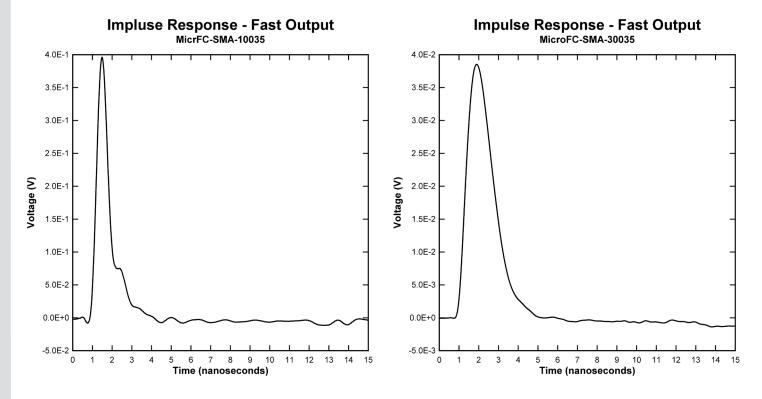
^{*} This data is acquired at a fixed overvoltage (2.5V above the VBr at room temperature, which is typically ~27V).

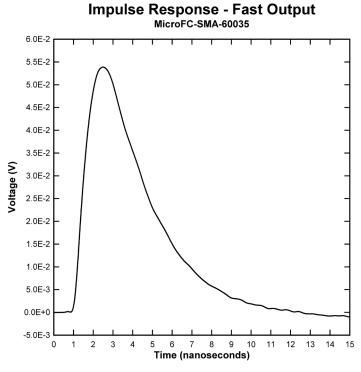




FAST OUTPUT SIGNALS

The oscilloscope graphs below show examples of measured waveforms from the fast output of 1mm, 3mm and 6mm sensors mounted on the SensL SMA product boards; the MicroFC-SMA-10035, MicroFC-SMA-30035 and MicroFC-SMA-60035. All measurements are obtained using a 2.5GHz bandwidth oscilloscope and a 50MHz, 50ps red (650nm) laser. No amplifier was used, and the output of the SMA product boards was directly connected to the oscilloscope using a 1m long, 50Ω coaxial cable.







C-Series Low Noise, Fast, Blue-Sensitive Silicon Photomultipliers DATASHEET



EVALUATION BOARD OPTIONS

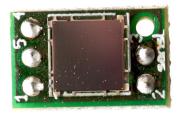
SMA BIASING BOARD (MicroFC-SMA-XXXXX)

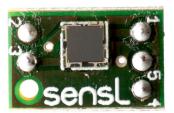
The MicroFC-SMA is a simple board designed to allow evaluation of the MicroFC SMT range of SiPM sensors. The board has three female SMA connectors for connecting the bias voltage, standard output from the anode and the fast output signal. The biasing and output line is laid out in such a way as to preserve the fast timing characteristics of the sensor.

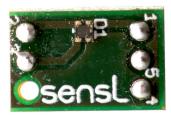
The MicroFC-SMA is recommended for users who require a plug-and-play set-up to quickly evaluate FC-Series SMT sensors with optimum timing performance. The board also allows the standard output from the anode to be observed at the same time as the fast output. The outputs can be connected directly to the oscilloscope or measurement device. The table below lists the SMA board connections.

Output	Function
Vbias	positive bias input (cathode)
Fout	fast output
Sout	standard output (anode)









PIN ADAPTER (MicroFC-SMTPA-XXXXX)

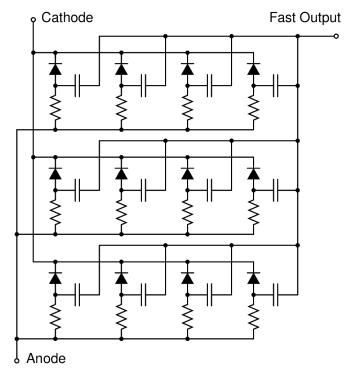
The SMT Pin Adapter board (SMTPA) is a small PCB board that houses the SMT sensor and has through-hole pins to allow its use with standard sockets or probe clips. This product is useful for those needing a quick way to evaluate the SMT package without the need for specialist surface-mount soldering. While this is a 'quick fix' suitable for many evaluations, it should be noted that the timing performance from this board will not be optimized and if the best possible timing performance is required, the MicroFC-SMA-XXXXX is recommended.

Pin	Commention	Function			
No. Connection		Positive bias	Negative bias		
1	anode	standard output (if unused connect to zero V)	negative bias input		
2	fast	fast output (if unused can be left open)	fast output (if unused can be left open)		
3	cathode	positive bias input	standard output (if unused connect to zero V)		
4	gnd	PCB gnd	PCB gnd		
5	n/c	do not connect	do not connect		

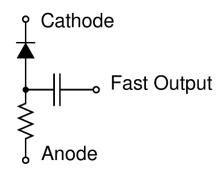




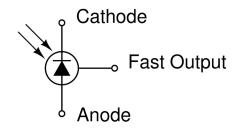
CIRCUIT SCHEMATICS



Simplified circuit schematic of the SensL SiPM showing only a 12 microcell example.



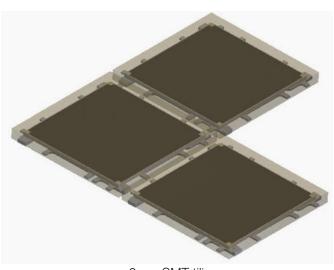
Circuit schematic of the SensL SiPM microcell, showing details of the Fast Output.



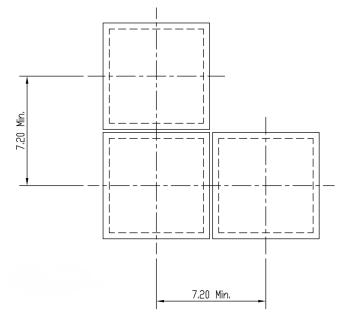
SensL SiPM component symbol.

TILING OF THE SMT PACKAGE

SensL has developed a market-leading, custom SMT package for the C-Series sensors. It is a compact, leadless, chip-scale package that is compatible with lead-free, reflow soldering processes. A clear encapsulant is used for optimal coupling to scintillators or fibre optic elements.



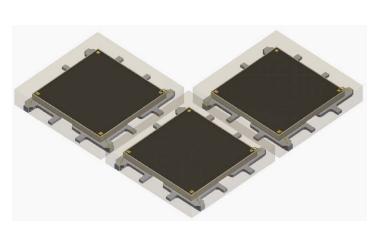
6mm SMT tiling.



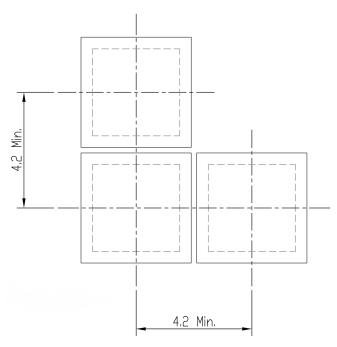


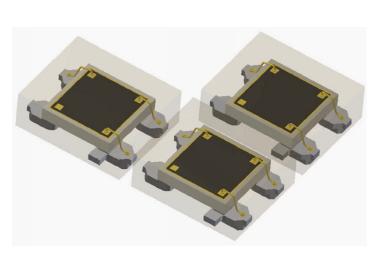


The dead-space between the sensor chip and the edge of the package has been minimized resulting in a package that can be tiled on 4 sides. This allows multiple devices to be configured into unique layouts for a wide range of custom applications. Two-dimensional tiling examples are illustrated for the 1mm, 3mm and 6mm packages. The distance between active areas is typically 1.2mm when tiled, but actual alignment and placement tolerances will depend on the accuracy of the user's assembly process. A Technical Note is available that gives advice on creating arrays of the SMT sensors.

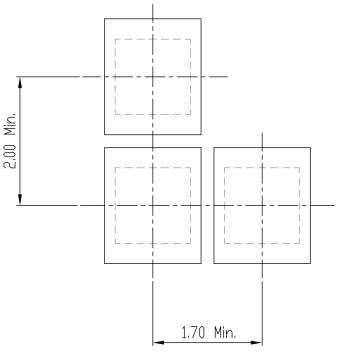


3mm SMT tiling.





1mm SMT tiling.

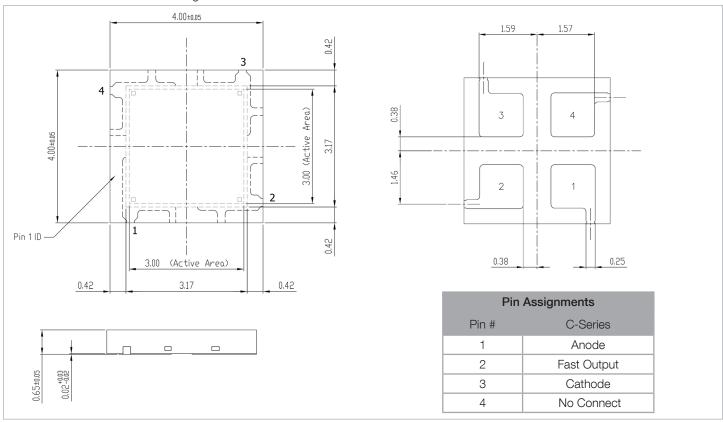




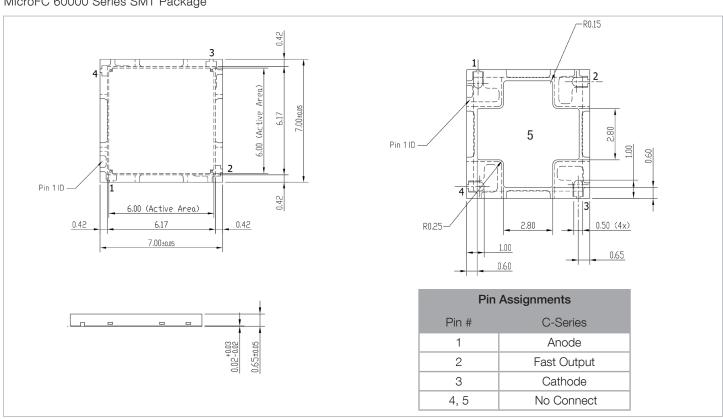


SCHEMATICS (All Dimensions in mm)

MicroFC 30000 Series SMT Package



MicroFC 60000 Series SMT Package



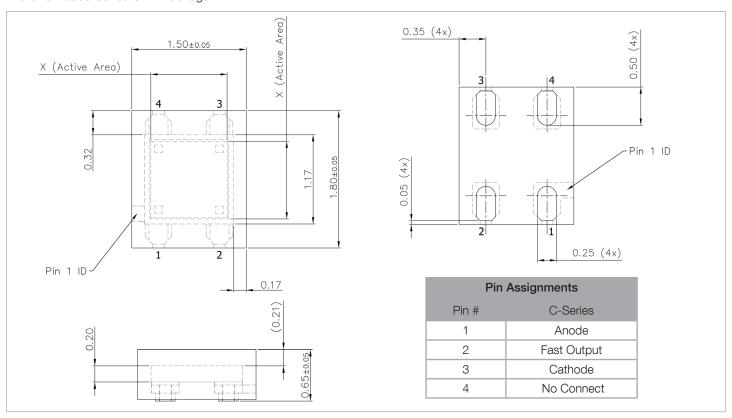


C-Series Low Noise, Fast, Blue-Sensitive Silicon Photomultipliers DATASHEET

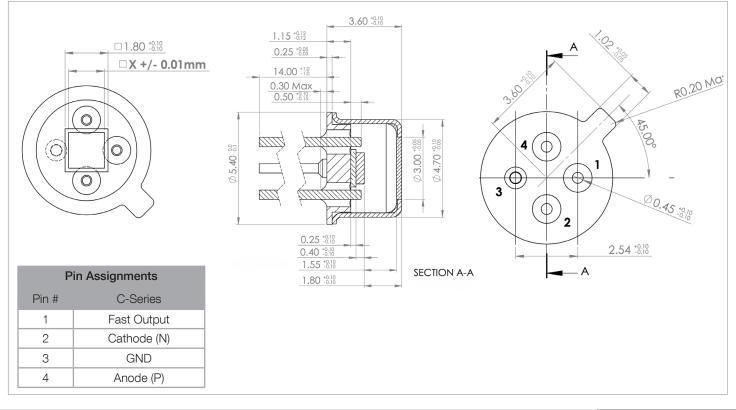


SCHEMATICS (All Dimensions in mm) - Continued

MicroFC 10000 Series SMT Package



MicroFC 10000 Series TO18 Package



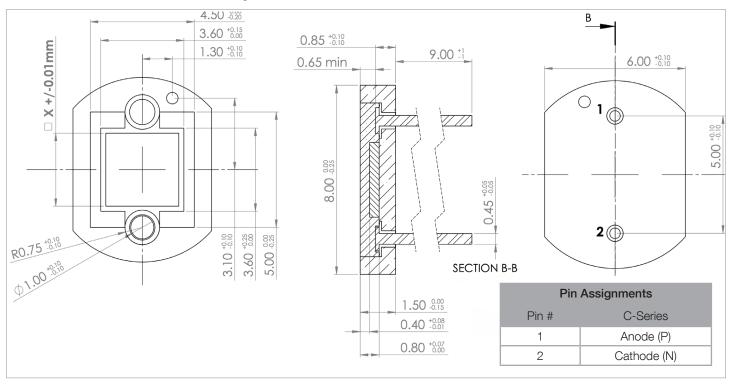


 $C\text{-Series} \ \mathsf{Low} \ \mathsf{Noise}, \ \mathsf{Fast}, \ \mathsf{Blue}\text{-}\mathsf{Sensitive} \ \mathsf{Silicon} \ \mathsf{Photomultipliers}$ DATASHEET

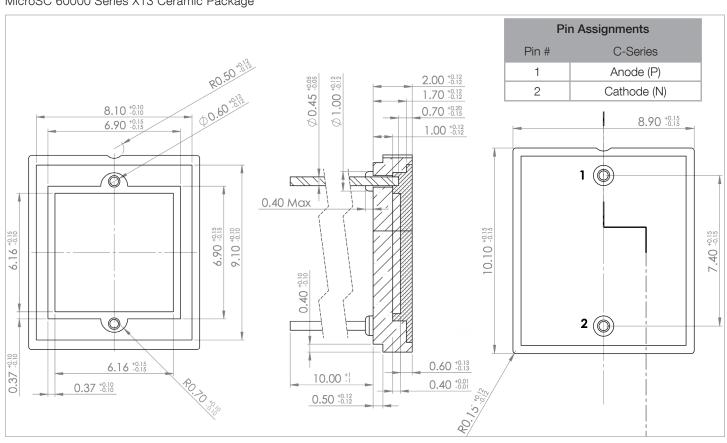


SCHEMATICS (All Dimensions in mm) - Continued

MicroSC 30000 Series X13 Ceramic Package



MicroSC 60000 Series X13 Ceramic Package

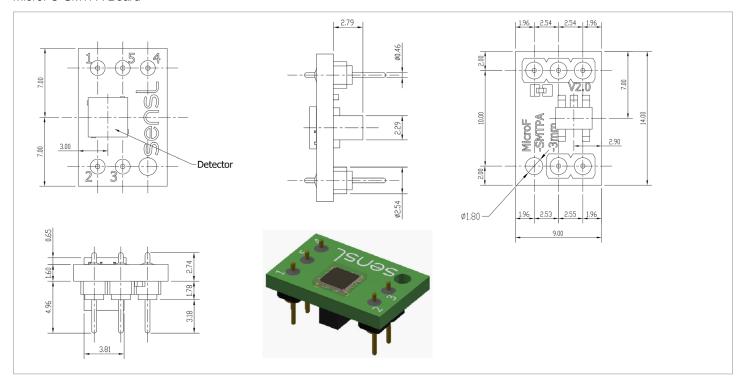




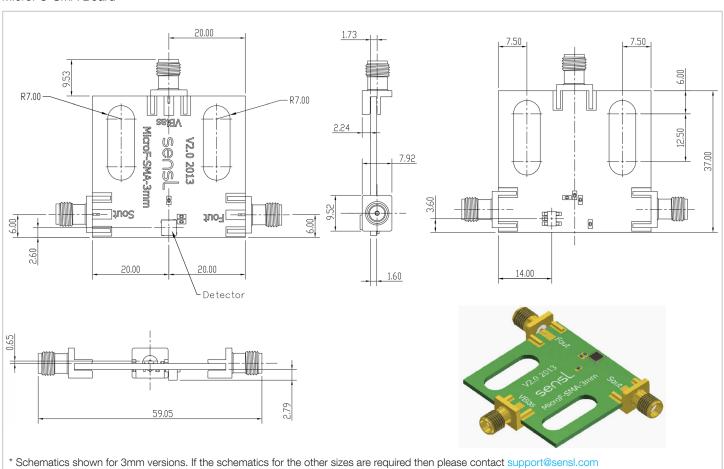
 $C\text{-Series} \ \mathsf{Low} \ \mathsf{Noise}, \ \mathsf{Fast}, \ \mathsf{Blue}\text{-}\mathsf{Sensitive} \ \mathsf{Silicon} \ \mathsf{Photomultipliers}$ DATASHEET



MicroFC-SMTPA Board *



MicroFC-SMA Board *







ORDERING INFORMATION

Product Code	Microcell size (Total number)	Sensor active area	Package type	Delivery options ^a
10000 Series				
MicroFC-10010-SMT			4-side tileable, surface mount package (SMT)	GP, TA, TR ^b
MicroFC-SMA-10010	10µm		SMT sensor mounted onto a PCB with SMA connectors for bias and output.	PK
MicroFC-SMTPA-10010	(2880 microcells)		SMT sensor mounted onto a pin adapter board.	PK
MicroFC-10010-X18			3-pin TO-18 package	PK
MicroFC-10020-SMT			4-side tileable, surface mount package (SMT)	GP, TA, TR ^b
MicroFC-SMA-10020	20µm	1mm x 1mm	SMT sensor mounted onto a PCB with SMA connectors for bias and output.	PK
MicroFC-SMTPA-10020	(1296 microcells)		SMT sensor mounted onto a pin adapter board.	PK
MicroFC-10020-X18			3-pin TO-18 package	PK
MicroFC-10035-SMT			4-side tileable, surface mount package (SMT)	GP, TA, TR ^b
MicroFC-SMA-10035			SMT sensor mounted onto a PCB with SMA connectors for bias and output.	PK
MicroFC-SMTPA-10035	35µm (576 microcells)		SMT sensor mounted onto a pin adapter board.	PK
MicroFC-10035-X18			3-pin TO-18 package	PK
MicroSC-10035-X13 ^d			2-pin ceramic package, epoxy fill	PK
MicroFC-10050-SMT			4-side tileable, surface mount package (SMT)	GP, TA, TR ^b
MicroFC-SMA-10050	50µm		SMT sensor mounted onto a PCB with SMA connectors for bias and output.	PK
MicroFC-SMTPA-10050	(324 microcells)		SMT sensor mounted onto a pin adapter board.	PK
MicroFC-10050-X18			3-pin TO-18 package	PK

^a The two-letter delivery option code should be appended to the order number, e.g) to recieve a MicroFC-60035-SMT in a Gel Pack, use MicroFC-60035-SMT-GP. The codes are as follows:

PK = ESD Package

GP = Gel Pack

 $WP = Waffle Pack ^c$

TA = Tape

TR = Tape and Reel b

^b The TR (Tape and Reel) delivery option has a minimum order quantity (MOQ) of 3000, and is available in multiples thereof.

[°]WP option only available for small quantity orders, please discuss with SensL sales.

^a NOTE: The 'SC' products have only 2 pins (anode and cathode) and therefore do not feature the fast output signal.





ORDERING INFORMATION (Continued)

Product Code	Microcell size (Total number)	Sensor active area	Package type	Delivery options ^a
30000 Series				
MicroFC-30020-SMT	20µm (10998 microcells)	3mm x 3mm	4-side tileable, surface mount package (SMT)	WP °, TA, TR b
MicroFC-SMA-30020			SMT sensor mounted onto a PCB with SMA connectors for bias and output.	PK
MicroFC-SMTPA-30020			SMT sensor mounted onto a pin adapter board	PK
MicroFC-30035-SMT	35µm (4774 microcells)		4-side tileable, surface mount package (SMT)	WP °, TA, TR b
MicroFC-SMA-30035			SMT sensor mounted onto a PCB with SMA connectors for bias and output.	PK
MicroFC-SMTPA-30035			SMT sensor mounted onto a pin adapter board	PK
MicroSC-30035-X13 ^d			2-pin ceramic package, epoxy fill	PK
MicroFC-30050-SMT	50µm (2668 microcells)		4-side tileable, surface mount package (SMT)	WP °, TA, TR b
MicroFC-SMA-30050			SMT sensor mounted onto a PCB with SMA connectors for bias and output.	PK
MicroFC-SMTPA-30050			SMT sensor mounted onto a pin adapter board	PK
60000 Series				
MicroFC-60035-SMT	35µm (18980 microcells)	6mm x 6mm	4-side tileable, surface mount package (SMT)	GP, TA, TR ^b
MicroFC-SMA-60035			SMT sensor mounted onto a PCB with SMA connectors for bias and output.	PK
MicroFC-SMTPA-60035			SMT sensor mounted onto a pin adapter board	PK
MicroSC-60035-X13 ^d			2-pin ceramic package, epoxy fill	PK

^a The two-letter delivery option code should be appended to the order number, e.g) to recieve a MicroFC-60035-SMT in a Gel Pack, use MicroFC-60035-SMT-GP. The codes are as follows:

PK = ESD Package GP = Gel Pack WP = Waffle Pack c TA = TapeTR = Tape and Reel b

^aNOTE: The 'SC' products have only 2 pins (anode and cathode) and therefore do not feature the fast output signal.



www.sensl.com sales@sensl.com +353 21 240 7110 (International) +1 650 641 3278 (North America)

^b The TR (Tape and Reel) delivery option has a minimum order quantity (MOQ) of 3000, and is available in multiples thereof.

^cWP option only available for small quantity orders, please discuss with SensL sales.